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TABLE OF CONTENTS

Volume 1

Keynote Address: The US Economic Recovery: The Good, The Bad and The Ugly	1
<i>Angelos Angelou</i>	
Keynote Address: Emerging Technologies in a Changing Economy	31
<i>David L. Bergeron</i>	
Keynote Address: The Semiconductor Recovery Driven By Innovation and Marketing Technology	61
<i>Jim Feldhan</i>	
Keynote Address: SNAPBACK: Why and How the Flow of Manufacturing Offshore Could Reverse	100
<i>G. Dan Hutcheson</i>	

SESSION 1: FAB PRODUCTIVITY I - SPONSORED BY APPLIED MATERIALS

Solutions for Agile Semiconductor Manufacturing	134
<i>Sanjiv Mittal, Helen Armer, Scott Watson</i>	
First Wafer Delay and Setup: How to Measure, Define and Improve First Wafer Delays and Setup Times in Semiconductor Fabs	156
<i>Peter Van Der Meulen, Martin Petraitis, Stefan Radloff, Blane Rhoads, Mario Abravanel, Dylan Steeg</i>	
Improving Processing Speed By Statistical Evaluation of Raw Tool Time	173
<i>Michael Rettelbach, Sebastian Werner</i>	
Developing a New Manufacturing Operation Policy Framework for Multiple Semiconductor Manufacturing Fabs	189
<i>Kyoung-Shik Jun</i>	
A Novel Approach to Visualizing Manufacturing Data: From Analysis to Diagnostic	207
<i>Franck Gasnier, Guillaume Hennion</i>	
Yield Optimal Dynamic Sampling: Modeling, Algorithm, Software, and ROI Analysis	223
<i>Dadi Gudmundsson, Mike Zhang</i>	

SESSION 2: GREEN MANUFACTURING

Emerging Greenhouse Gas Regulations and The Implications for the Semiconductor Industry	234
<i>Bruce Klafter</i>	
Propose an Optimized LEED Green FAB Model for Semiconductors	252
<i>Tony Chen, Arthur Chuang</i>	
Limitations in the Use of CEMs for Quantifying Total PFC Emissions	272
<i>Tim Higgs</i>	
The Feasibility of Alternative and Renewable Energy in the Semiconductor Industry	286
<i>Mike Frisch</i>	
BIM, LEED, or Get Out of the Way?	336
<i>Allan Chasey</i>	
A Simple Method for Estimating the Amount of Feedwater Required to Operate a Semiconductor Process Tool	364
<i>Teresa Zhang, Mark Denome, Andreas Neuber</i>	

SESSION 3: STATISTICAL METHODS 1

Estimation of Variability from Processes with Nested Structure	384
<i>Diane K. Michelson</i>	
Using Correct Measurement System Metrics to Evaluate Gauge Capability	404
<i>Abraham Chen, J. DaRon Huffaker, Yaohua Zhang</i>	
Setting Specifications Through Surrogate Parameters and Monte Carlo Simulation	451
<i>Donald McCormack</i>	
Fitting a Median Plane to 1/f Noise Data	462
<i>Ed Russell, Vijay Krishnamurthy</i>	

Going Nonlinear: On Modeling and Nonlinear Regression	481
<i>Theresa Utlaut, Kevin Anderson</i>	
Split Testing: Batch Effects, Systematic Effects and Sloth	512
<i>Andrew Brendler, Patrick McCutcheon</i>	

SESSION 4: EQUIPMENT PRODUCTIVITY I

Building an Effective Defect Pareto Through Design Integration	539
<i>Allen Park, Ellis Chang</i>	
Sealing in Success: The Devil Is in the Details	556
<i>Dalia Vernikovsky, Drew Elliott</i>	
A Modular Design Approach to Automation Systems	580
<i>Ghulam Mustafa, Larry Wise</i>	
Monitoring of Remote Plasma Source and Chemical/Thermal Chamber Cleans	600
<i>Jerome Cannon, Matthew Minton, Eric McCormick</i>	
Analytical Techniques Drive Advances in Cleaning Chamber Components	618
<i>Jason Wang, Satya Adamala, Joe Sommers</i>	
Laser Center Finder as an Early Indicator of Robot Condition and Bearing Performance	631
<i>Lay Huat Ang, Smark Wu, Frederic Bouchard, Andrew Clearwater</i>	

SESSION 5: FAB PRODUCTIVITY II

Plansim: Capacity Planning Based on Linear Programming	646
<i>Martin Romauch, Georg Seidel, Hermann Gold, Walter Laure</i>	
Scheduling Diffusion Area in Real Time	663
<i>Tanju Yurtsever, Jenn Johns, Erhan Kutanoglu</i>	
Optimizing Manual Material Delivery with Real-Time Location and Workflow Technologies	690
<i>Parris Hawkins, Jason Maughan, Rick Sheffield</i>	
Material Tracking Model for Small Lot Manufacturing	705
<i>James Moyne</i>	
Using Idling-Machine Model to Reduce Manufacturing Cost in Freescale Semiconductor	719
<i>Yiwei Cai</i>	
Enabling Timely Revolutions in the Performance of Multi-Product Fabs	729
<i>Charles Weber, Asser Fayed</i>	

SESSION 6: ESH SOLUTIONS

Implanter Exhaust Savings - Energy/Capital	774
<i>Steve Russo</i>	
Drivers For Environmental Information Exchange: A Electronics Manufacturing Perspective	790
<i>John Messina</i>	

Volume 2

Sustainable and Energy Efficient Semiconductor Manufacturing	811
<i>Andreas Neuber, Krishna Vepa, Parth Sethia</i>	
D1D LEED Energy Savings Overview	839
<i>Ryan Shelby</i>	

SESSION 7: STATISTICAL METHODS II

Calculating Statistics on Very Large Data Sets	854
<i>Bruce Aldridge</i>	
Accelerating Manufacturing Business Intelligence. A Semiconductor Manufacturing Example.	876
<i>Mike Hackerott</i>	
Optimization Solvers in Run-To-Run Control	900
<i>Courtney Hanish</i>	

Lot and Wafer Sampling Plan Methodology for Outgoing DPM Control	935
<i>Abraham Chen, Yaohua Zhang, J. DaRon Huffaker</i>	
Statistical DOE and Analysis for Illuminator	968
<i>Helen Hu</i>	

SESSION 8: EQUIPMENT PRODUCTIVITY II

Development of a CU Polish Process for the SpeedFam Auriga C	984
<i>Eric Brannon, Chris Nauert, Michael Wedlake</i>	
Improvement of End Point Detection in Contact Hole Etching	1001
<i>Toshikazu Hanawa, Kazuhide Fukaya, Taikan Ando, Masashi Sahara</i>	
Equipment Productivity Improvement Obtained By Robot Speed Increases, Utilizing a New End Effector Technology	1016
<i>Michael Dailey</i>	
New Predictive Maintenance Method Prevents Wafer Handling Malfunction in High Volume Manufacturing Environment	1025
<i>Yigal Tomer, Ein Harod</i>	
Improved Film Production in a High Volume Fab	1053
<i>Craig Ramsey</i>	
Optimized Pad Conditioning for STI CMP	1072
<i>Gene Davis, David Slutz</i>	

SESSION 9: E-MANUFACTURING

Factory Considerations for Interface A Applications	1095
<i>Larry Barto, Robert Russin</i>	
Time Synchronization on a Budget: An Incremental Implementation Roadmap	1116
<i>Alan Weber, Jim Hollister</i>	
MultiGEM, A Poor Man's EDA	1132
<i>Chris Winemiller</i>	
Implementation of MIMO R2R Control Regulation on Furnace Processes	1148
<i>Agnès Roussy, Benoist Richard, Laurent Brun, Denis Pompier, Jacques Pinaton, Christophe Macé, Nicolas Csejtei</i>	
Accelerating Yield Entitlement - Core Information Management Hub for Semiconductor Operations	1175
<i>Michael Downer</i>	
Reducing The CoO of Factory-Wide R2R Through Selection & Deployment of a Commercial System	1190
<i>Luke Mielke</i>	

SESSION 10: CONCEPTS IN MANUFACTURING - SPONSORED BY MAX I. E. G.

Utilizing the Right Machine Speed Model to Minimize Cost	1214
<i>Marino F. Arturo</i>	
Overcoming the Limitations of Lean, Six Sigma, and the Theory of Constraints in Reentrant Factories	1229
<i>James Ignizio</i>	
The Importance of EEQA Methodology and Implementation in the Semiconductor Industry	1258
<i>Steve Geist, Shigeru Kobayashi, Michio Honma, Gino Crispieri</i>	
5D, The R-evolution to Fab Management	1274
<i>Arthur Chuang</i>	
3D Interconnect / TSV Manufacturing: Lessons Learned	1312
<i>Andrew C. Rudack, Raymond Caramto</i>	

SESSION 11: YIELD & METROLOGY - SPONSORED BY TERADATA CORPORATION

Smarter Defect Inspection By Use of Design Data Information	1334
<i>Remo Kirsch, Ulrich Zeiske, Mirko Beyer</i>	
A Versatile Automated Defect Detection and Classification System for Assembly, Test Semiconductor Manufacturing	1353
<i>Bonnie Bennett, Jeff Pettinato, Asaad Said, Lina Karam</i>	

Immersion and Dry Lithography Monitoring for Flash Memories (After Develop Inspection and Photo Cell Monitor) Using a Darkfield Imaging Inspector with Advanced Binning	1367
<i>P. Parisi, A. Mani, C. Perry-Sullivan, J. Kopp, G. Simpson, C. Brown, M. Renis, M. Padovani, C. Severgnini, P. Piacentini, P. Piazza, A. Beccalli</i>	
Using Virtual Metrology to Improve Productivity and Reduce Waste: Approaches, Challenges, and a Case Study of CD Control at Etch.....	1386
<i>James Moyne</i>	
Microstructural Evolution of Process Induced Defects in Metal Layers of 180nm Al-Cu Interconnect Architectures.....	1412
<i>Mark Johnson, P. S. Frankwicz, P. Kurkowski, C. Viera, T. Moutinho</i>	
Uniformity Monitoring of a Laser Ultrafast Anneal Tool In a Production Environment Using KLA-Tencor SURFmonitor	1431
<i>Dominik Thron, Jan Holub, Andreas Woocko, Sanda Radovanovic</i>	

SESSION 12: FAB TRANSITION STRATEGY UPDATE

Fab Transition Opening Remarks.....	1449
<i>Joe Draina</i>	
450 mm Program Update.....	1454
<i>Tom Jefferson</i>	
ISMI NGF Program Update.....	1490
<i>Olaf Rothe</i>	

POSTERS

Developing Performance from Within Starts with Just One Drop.....	1509
<i>Ron McDavid</i>	
The European CLP Regulation - Changes to REACH Adopting GHS Criteria.	1525
<i>Lauren Crane</i>	
45nm Cu Damascene Structure Measured By Optical CD for Advanced Process Control.....	1541
<i>Cyril Arsac, D. Galpin, C. Monget, S. Chhun, V. Caubet-Hilloutou, M. Mellier, O. Doctot, C. Regnier, A. Tarnowka, A. Eliyahu</i>	
ARDE in Via Etching	1542
<i>Rod Hill</i>	
Enhanced Equipment Quality Assurance (EEQA) Methodology, Concepts and Results of Demonstrating Its Application and Benefits.....	1552
<i>Shigeru Kobayashi, Steve Geist, Michio Honma, Gino Crispieri</i>	
Joint Maintenance and Operations Decision Making in Flexible Manufacturing Systems.....	1568
<i>Merve Celen, Mike Cholette, Alexander Bleakie, Dragan Djurdjanovic</i>	
Virtual Metrology for In-Situ Etch Rate Prediction in a Plasma Etch Process.....	1584
<i>Bhalinder Gill</i>	
Predictive and Preventive Maintenance (PPM) Tools and Performance Analytics for Semiconductor Equipment.....	1600
<i>Edzel Lapira</i>	
Context Dependant Degradation Modeling of a PECVD Tool.....	1601
<i>Dragan Djurdjanovic, Michael Cholette, Alexander Bleakie, Merve Celen</i>	
AMHS Scheduling in Semiconductor Manufacturing.....	1617
<i>Emrah Zarifoglu, Erhan Kutanoglu, John Hasenbein</i>	
Control Performance Assessment for EWMA Controllers.....	1635
<i>Xiaojiang Jiang, Jin Wang, John Stuber, Thomas F. Edgar</i>	
Job Scheduling Optimization in Semiconductor Manufacturing Via Simulation-Based Approximate Dynamic Programming	1636
<i>Jose Ramirez-Hernandez, Emmanuel Fernandez</i>	
Author Index	